

Scaled holder for semiconductor wafer etching

Patent Number: DE19728962
Publication date: 1999-01-07
Inventor(s): MORITZ HANS (DE); KRETSCHMER HANS DR RER NAT (DE)
Applicant(s): SIEMENS AG (DE)
Requested Patent: DE19728962
Application Number: DE19971028962 19970630
Priority Number(s): DE19971028962 19970630
IPC Classification: H01L21/306; H01L21/68
EC Classification: H01L21/00S2D8D
Equivalents:

Abstract

The holder has a cast elastic body (1) with concentric circular lips (2,3) between which electrical contact leaf springs (14-17) are provided and a channel section (6) opens from the end of a vacuum line (4). A relatively large hole (7) through the body is closed by a disc (8) snapped into a groove (9). At the high temperature of etching, pressure is built up in the space (11) between the disc and the wafer. To avoid consequential damage to the wafer a relief duct (12) is provided at atmospheric pressure.

Data supplied from the esp@cenet database - I2